



Material Composition Declaration

EPC2212

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/9/2019
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	6.4 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	5.4032	84.8976	87.0320	848976
	Silicon oxide	7631-86-9	0.0209	0.3276		3276
	Silicon nitride	12033-89-5	0.0066	0.1041		1041
	Gallium nitride	25617-97-4	0.0255	0.4006		4006
	Aluminum	7429-90-5	0.0407	0.6396		6396
	Aluminum nitride	24304-00-5	0.0061	0.0965		965
	Titanium	7440-32-6	0.0009	0.0144		144
	Titanium nitride	25583-20-4	0.0036	0.0573		573
	Copper	7440-50-8	0.0014	0.0213		213
	Tungsten	7440-33-7	0.0011	0.0169		169
	Polyimide		0.0290	0.4561		4561
Under Bump Metal	Titanium	7440-32-6	0.0012	0.0182	1.5360	182
	Nickel	7440-02-0	0.0344	0.5400		5400
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0622	0.9777		9777
Solder Bump	Tin	7440-31-5	0.7094	11.1462	11.4320	111462
	Silver	7440-22-4	0.0182	0.2858		2858
	Copper	7440-50-8	0.0000	0.0000		0
Sum in total:			6.3644	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.